

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2904928

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SIMON JOHN MOLLOY	02/07/2014
CHRISTOPHER BOGUSLAW KOCON	02/06/2014
JOHN MANNING SAVIDGE NEILSON	06/16/2014
HONG YANG	02/06/2014
SEETHARAMAN SRIDHAR	02/06/2014
HIDEAKI KAWAHARA	02/06/2014
RECEIVING PARTY DATA	
Name:	TEXAS INSTRUMENTS INCORPORATED
Street Address:	12500 TI BOULEVARD, M/S 3999
City:	DALLAS
State/Country:	TEXAS
Postal Code:	75243
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14175488
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Email:	uspto@ti.com
Correspondent Name:	TEXAS INSTRUMENTS INCORPORATED
Address Line 1:	12500 TI BOULEVARD, M/S 3999
Address Line 4:	DALLAS, TEXAS 75243
ATTORNEY DOCKET NUMBER:	TI-73462
NAME OF SUBMITTER:	ARLENE J. SIMON
SIGNATURE:	/Arlene J. Simon/
DATE SIGNED:	06/19/2014
Total Attachments: 4	
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Serial No.

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made,

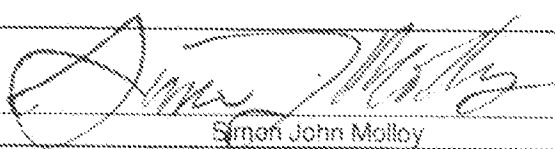
WHEREAS, TEXAS INSTRUMENTS INCORPORATED, a corporation organized and existing under the laws of the State of Delaware, with a place of business at 12500 TI Boulevard, M/S 3999, Dallas, Texas 75243, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon, as well as to U.S. Provisional Application No. 61/762,189, filed February 7, 2013;

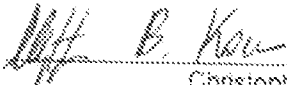
NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application(s) and all patents which may be granted therefore, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TEXAS INSTRUMENTS INCORPORATED, as assignee of my entire right, title and interest.

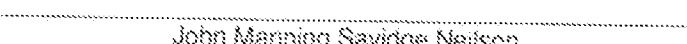
I also hereby sell and assign to TEXAS INSTRUMENTS INCORPORATED, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including the right to file applications and obtain patents under the terms of the Paris Convention for the Protection of Industrial Property, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

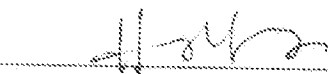
I hereby further agree that I will communicate to said TEXAS INSTRUMENTS INCORPORATED, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TEXAS INSTRUMENTS INCORPORATED, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

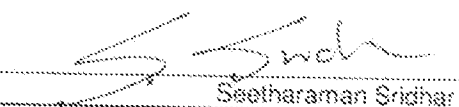
IN WITNESS WHEREOF, I hereunto set hand and seal this day and year:

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
APPLICATION NO(S)	
SIGNATURE OF INVENTOR AND NAME	 Simon John Molloy
DATE	2/7/14
RESIDENCE (CITY AND STATE)	Allentown, PA

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	 Christopher Boguslaw Koon
DATE	2/6/2014
RESIDENCE (CITY AND STATE)	Mountain Top, PA

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	 John Manning Savidge Neilson
DATE	
RESIDENCE (CITY AND STATE)	Norristown, PA

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	 Hong Yang
DATE	2/6/2014
RESIDENCE (CITY AND STATE)	Richardson, TX

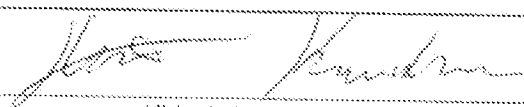
TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	 Seetharaman Sridhar
DATE	2/6/2014
RESIDENCE (CITY AND STATE)	Richardson, TX

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	_____ Christopher Boguslaw Koon
DATE	
RESIDENCE (CITY AND STATE)	Mountain Top, PA

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	_____ John Marling Savidge Neilson
DATE	6/16/11
RESIDENCE (CITY AND STATE)	Norristown, PA

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	_____ Hong Yang
DATE	
RESIDENCE (CITY AND STATE)	Richardson, TX

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	_____ Seetharaman Sridhar
DATE	
RESIDENCE (CITY AND STATE)	Richardson, TX

TITLE OF INVENTION	REDUCTION OF POLYSILICON RESIDUE IN A TRENCH FOR POLYSILICON TRENCH FILLING PROCESSES
SIGNATURE OF INVENTOR AND NAME	 Hideaki Kawahara
DATE	02 / 06 / 2014
RESIDENCE (CITY AND STATE)	Plano, TX

After recording, return Assignment to:

Texas Instruments Incorporated
PO Box 655474, M/S 3999
Dallas, TX 75265